WHAT IS CLAIMED IS:

1. A method of making a package, comprising:

preparing a tray that retains a desiccant;

providing one or more semiconductor devices on the tray;

heating the tray; and

sealing the tray in a moisture-proof container.

2. The method according to claim 1, wherein the tray and the desiccant retained therein are recovered after use.

3. A method of reusing a desiccant, comprising:

recovering a tray in which a desiccant is retained;

providing one or more semiconductor devices on the tray;

heating the tray; and

sealing the tray in a moisture-proof container.

4. A tray for containing semiconductor devices, comprising:

a plurality of pockets for accommodating one or more semiconductor devices having individual packages; and

a retainer that retains a desiccant,

wherein the tray sustains enough heat to substantially remove any moisture absorbed by the individual packages.

5. The tray according to claim 4, wherein the retainer includes a groove in which the desiccant is placed, and a cover to retain the desiccant in the groove.